



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



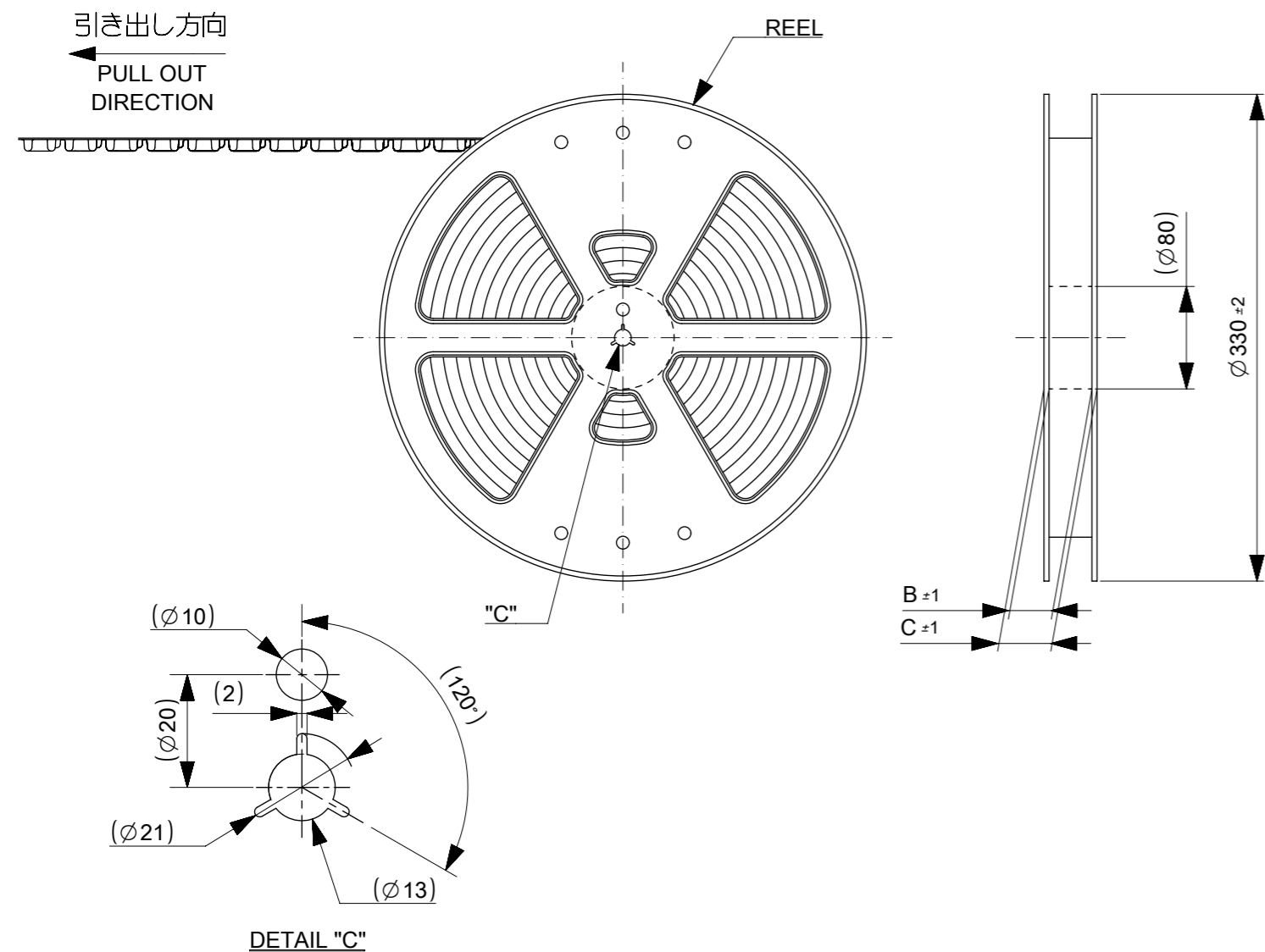
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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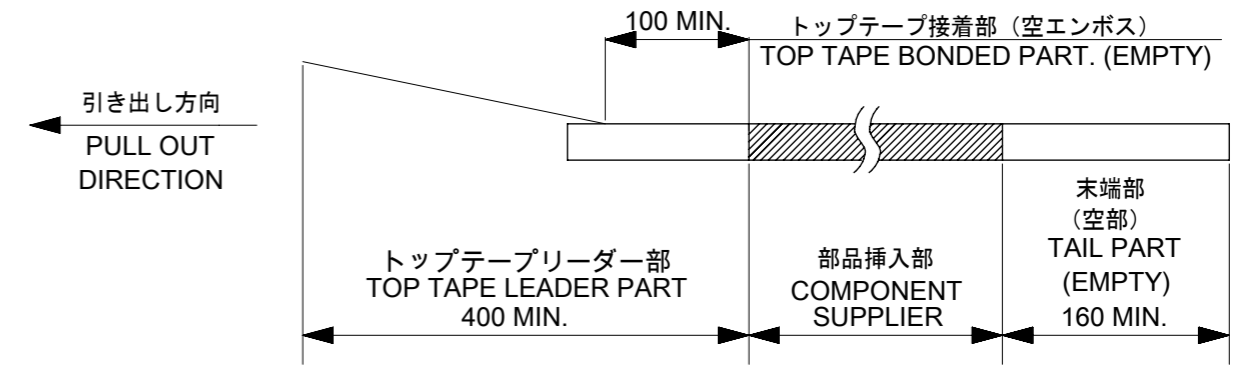
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





注記 NOTES:

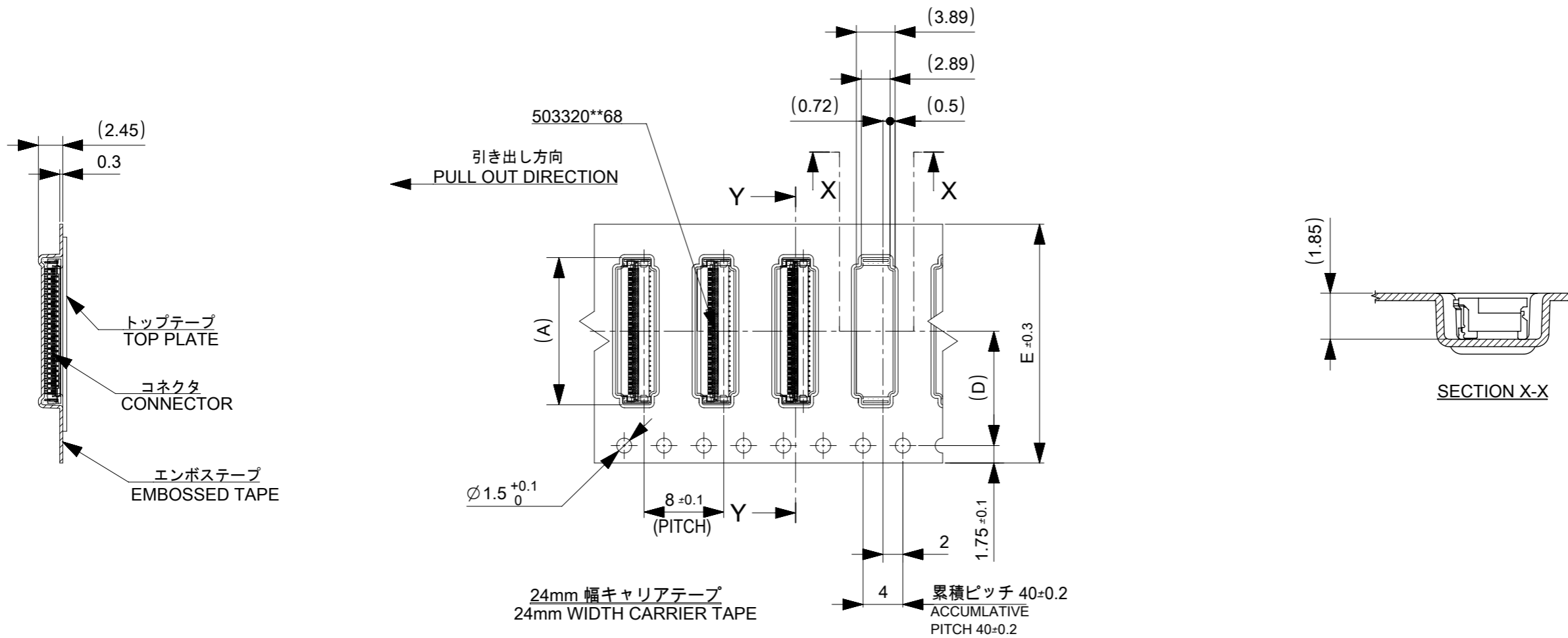
- 製品詳細寸法については図面 5033201000 を参照下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, SEE 5033201000
- 梱包数量: 3000 個 / リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- 材料 MATERIAL
キャリアテープ (CARRIER TAPE): ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) リサイクル材を含む
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV & RoHS COMPLIANT

MATERIAL NO. 503320**60

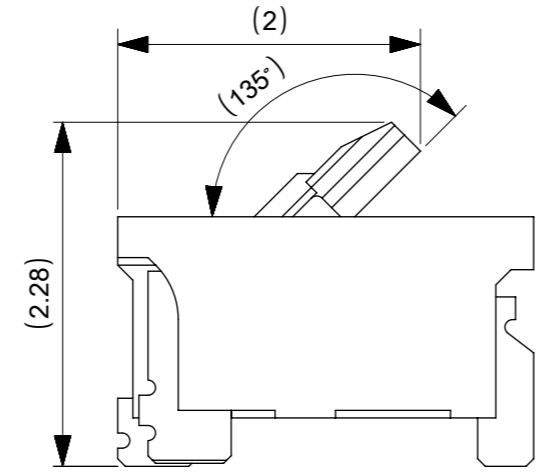
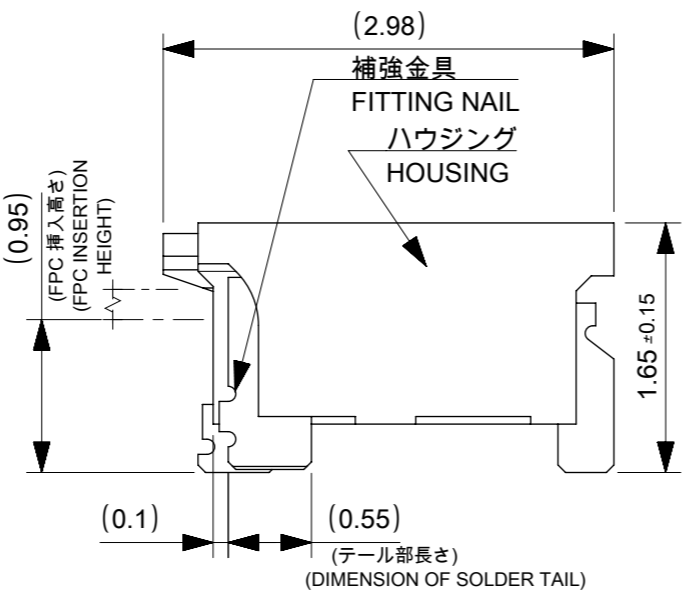
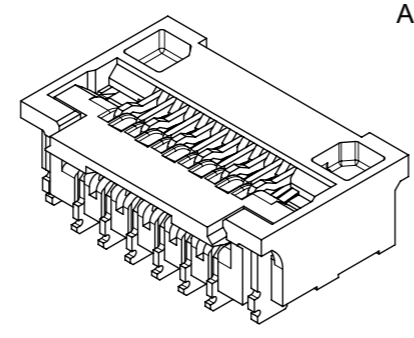
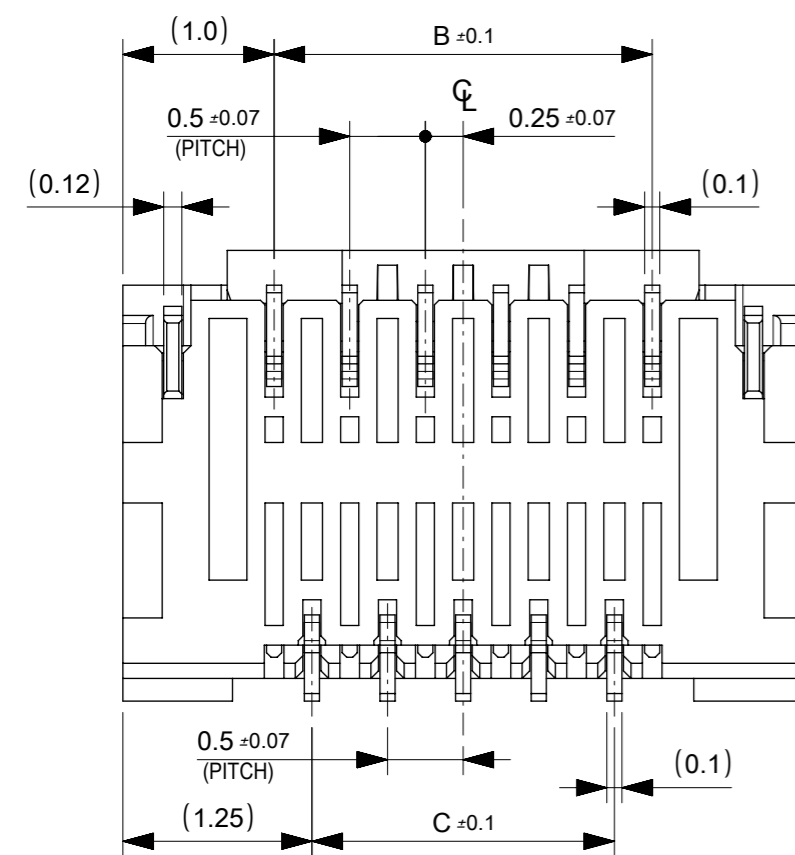
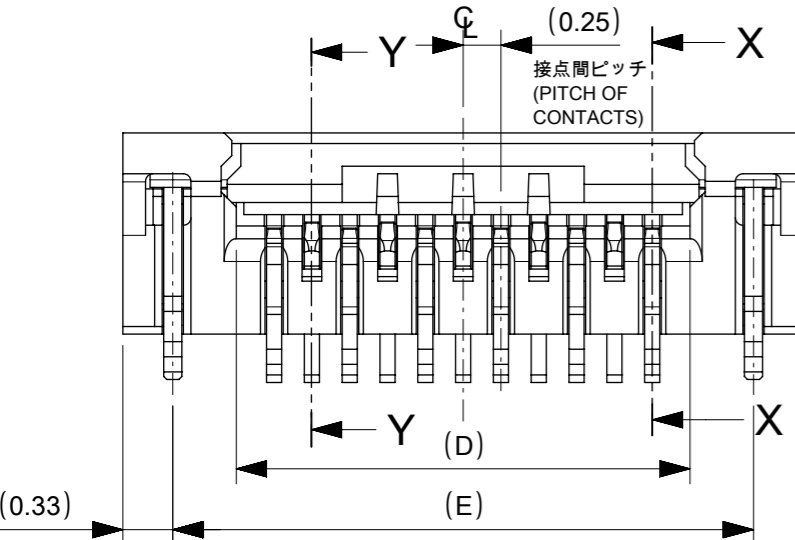
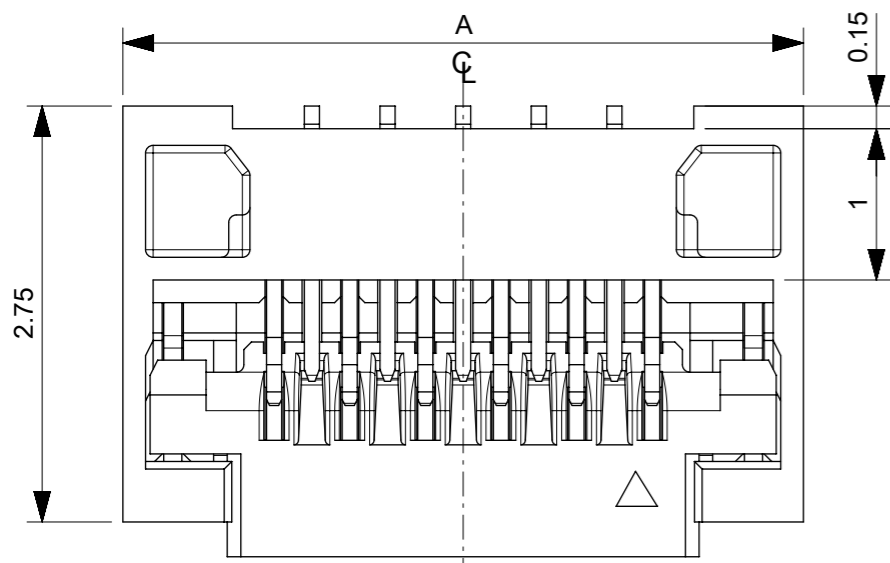
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									
REDRAW	2015/12/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION UNITS	SCALE	molex			
	2015/12/24	ANGULAR TOL ± °		MM	---				
	EC NO.: 102256 DRWN: VNANDAM CHK'D: HIJIMA APPR: YNOGAWA	4 PLACES	±	DRWN BY	DATE	0.25MM PITCH FPC CONN HGT=1.65 HSG ASSY EMBOSSED TAPE PACKAGE			
		3 PLACES	±	VNANDAM	2015/12/07				
		2 PLACES	±	CHK'D BY	DATE	PRODUCT CUSTOMER DRAWING			
		1 PLACE	±	HIJIMA	2015/12/24				
0 PLACES	±	APPR BY	DATE	SERIES	MATERIAL NUMBER	CUSTOMER			
			YNOGAWA	2015/12/24	503320	SEE CHART	GENERAL		
A	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWING SIZE	THIRD ANGLE PROJECTION	DOCUMENT NUMBER	DOC TYPE	DOC PART	SHEET NUMBER
				A3		5033200000	PSD	000	1 OF 2



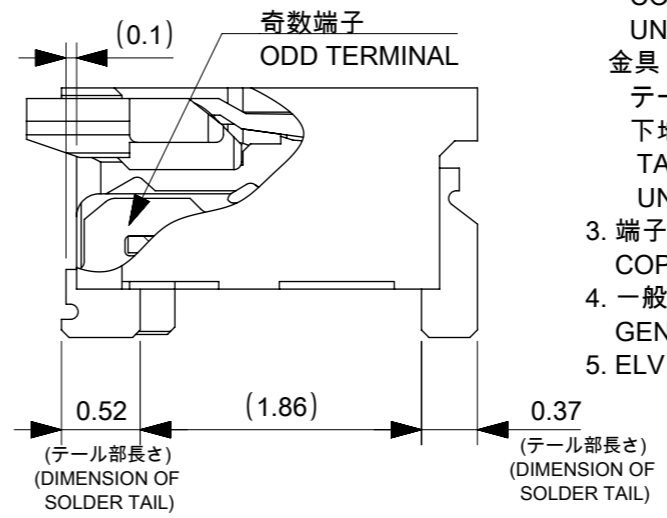
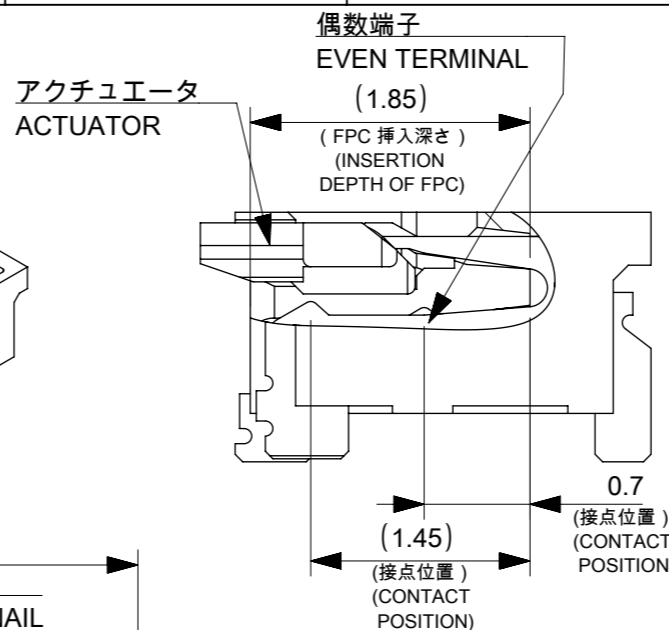
24	11.5	29.4	25.4	12.3	5033204160	41
				11.3	5033203760	37
				8.3	5033202560	25
E キャリアテープ幅 CARRIER TAPE WIDTH		(D)	C	B	(A)	EMBOSSSED PACKAGE オーダー番号 ORDER NO. 極数 MATERIAL NO. 503320**60 CKT

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REDRAW EC NO: 102256 DRWN: VNANDAM CHK'D: HIJIMA APPR: YNOGAWA	2015/12/07	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE	
	2015/12/24	ANGULAR TOL ± °	MM	---	
	2015/12/24	4 PLACES ±	DRWN BY	DATE	
		3 PLACES ±	VNANDAM	2015/12/07	
		2 PLACES ±	CHK'D BY	DATE	
		1 PLACE ±	HIJIMA	2015/12/24	
	0 PLACES ±	APPR BY	DATE	PRODUCT CUSTOMER DRAWING	
		YNOGAWA	2015/12/24	DRAWING SIZE	THIRD ANGLE PROJECTION
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	A3	SERIES: 503320 MATERIAL NUMBER: SEE CHART CUSTOMER: GENERAL	
				DOCUMENT NUMBER: 5033200000 DOC TYPE: PSD DOC PART: 000 SHEET NUMBER: 2 OF 2	



アクチュエータ開放位置
ACTUATOR OPENING
POSITION



注記 NOTES:

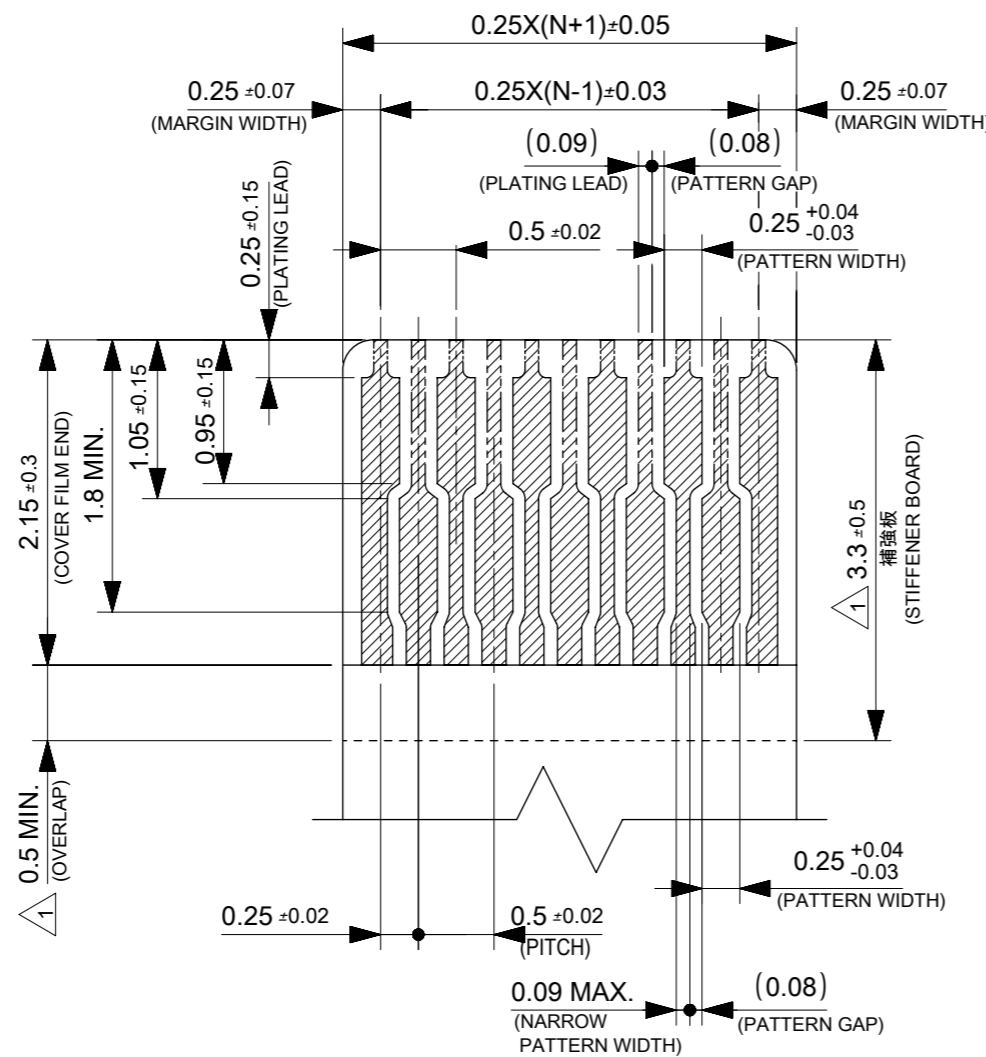
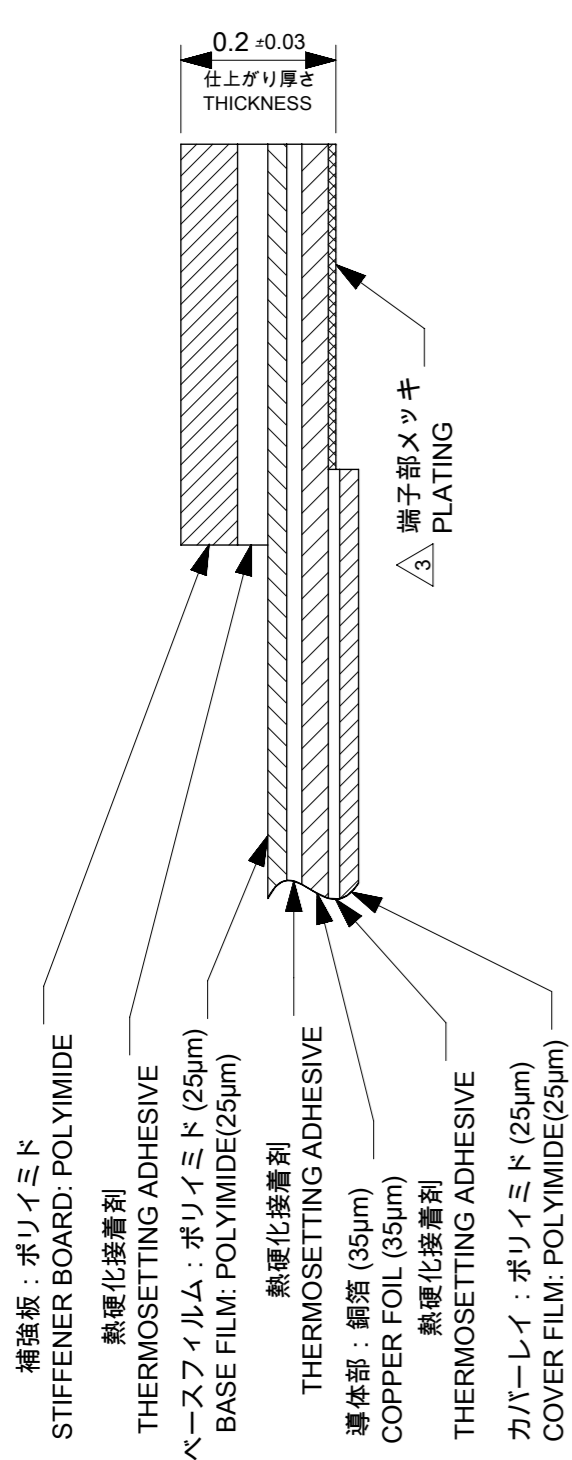
- 使用材料 MATERIALS
 ハウジング : 液晶ポリマー(ガラス充填、UL94V-0、ベージュ)
 アクチュエータ : ポリアミド(ガラス充填、UL94HB、黒色)
 奇数端子 : 銅合金
 偶数端子 : 銅合金
 補強金具 : 銅合金
 HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED, BEIGE)
 ACTUATOR : POLYAMIDE (GLASS FILLED, BLACK)
 ODD TERMINAL : COPPER ALLOY
 EVEN TERMINAL : COPPER ALLOY
 FITTING NAIL : COPPER ALLOY
- メッキ仕様 PLATING
 端子 TERMINAL
 テール部 : 部分金メッキ
 接点部 : 部分金メッキ 0.1μm MIN.
 下地 : ニッケルメッキ 1.0μm MIN.
 TAIL AREA : SEPARATED GOLD PLATING
 CONTACT AREA : SEPARATED GOLD PLATING 0.1μm MIN.
 UNDER PLATING : NICKEL PLATING 1.0μm MIN.
 金具 FITTING NAIL
 テール部 : スズメッキ 0.5μm MIN.
 下地 : ニッケルメッキ 1.0μm MIN.
 TAIL AREA : TIN PLATING 0.5μm MIN.
 UNDER PLATING : NICKEL PLATING 1.0μm MIN.
- 端子、補強金具のコプラナリティーは0.1以下とする
 COPLANARITY OF SOLDER TAILS AND FITTING NAILS : 0.1MAX.
- 一般公差 : ±0.3
 GENERAL TOLERANCES: ±0.3
- ELV & RoHS COMPLIANT.

11.34	10.5	9.5	10.0	12.0	5033204160	41
10.34	9.5	8.5	9.0	11.0	5033203760	37
7.34	6.5	5.5	6.0	8.0	5033202560	25
E	D	C	B	A	EMBOSSED PACKAGE	極数
オーダー番号 ORDER NO.						CIRCUITS
CONNECTOR SERIES NO. 503320**68						

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REDRAW EC NO: 102256 DRWN: VNANDAM CHK'D: HIIJIMA APPR: YNOGAWA	2015/12/07	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE	
	2015/12/24	ANGULAR TOL ± 1.0 °	MM	20:1	
	2015/12/24	4 PLACES ±	DRWN BY	DATE	
		3 PLACES ±	VNANDAM	2015/12/07	
		2 PLACES ±	CHK'D BY	DATE	
	1 PLACE ±	HIIJIMA	2015/12/24		
	0 PLACES ±	APPR BY	DATE		
		YNOGAWA	2015/12/24		
		DRAWING SIZE	THIRD ANGLE PROJECTION		
		A3			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			

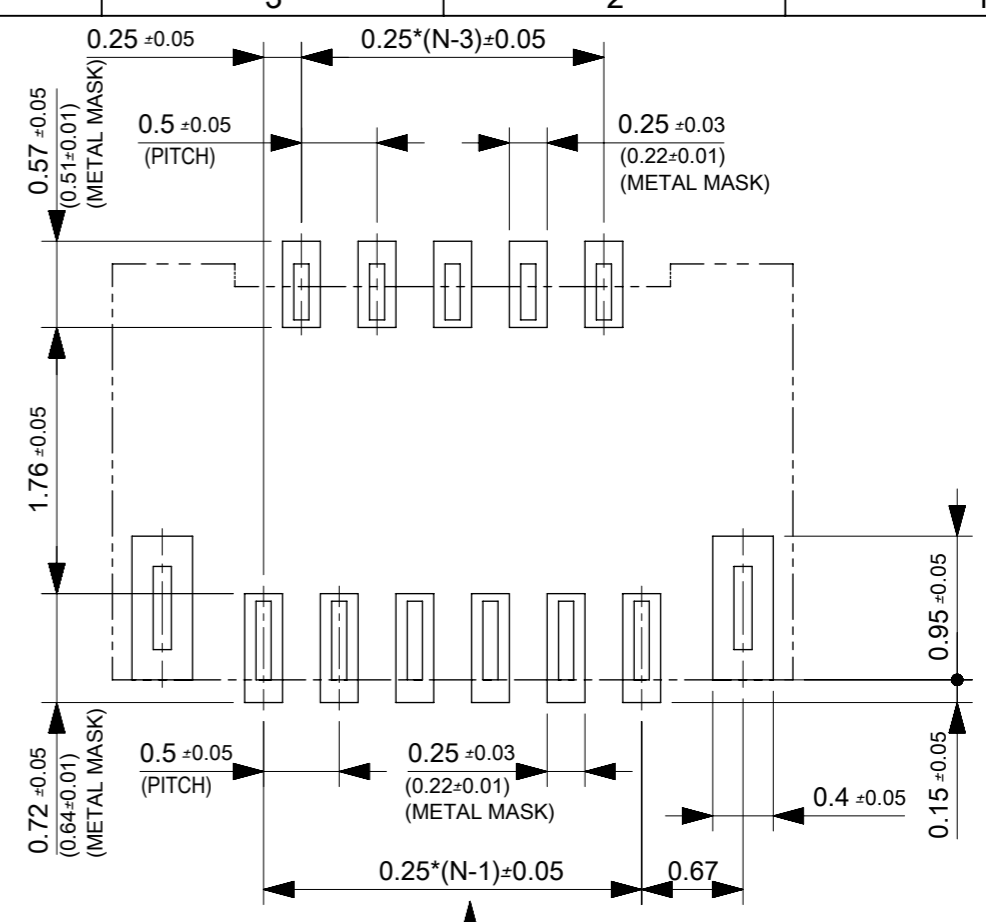
PRODUCT CUSTOMER DRAWING		
SERIES	MATERIAL NUMBER	CUSTOMER
503320	SEE CHART	GENERAL
DOCUMENT NUMBER	DOC TYPE	DOC PART
5033201000	PSD	000
SHEET NUMBER		
1 OF 2		



適合する FPC 推奨寸法
 APPLICABLE FPC
RECOMMENDED DIMENSION
 (端子部仕上げり厚さ : 0.2±0.03)
 (THICKNESS: 0.2±0.03)

注記 NOTES:

- 1 補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を 0.5mm 以上としてください
 WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM
- 2 推奨マスク厚 : 100µm
 推奨マスク開口率 : 80%
 RECOMMEND SCREEN THICKNESS : 100µm
 RECOMMEND SCREEN OPEN RATIO : 80%
- 3 FPC パターンのメッキ仕様は
 金メッキ : 0.1µm 以上
 下地ニッケルメッキ : 2~6µm
 FPC PATTERN PLATING
 GOLD PLATING : 0.1µm MINIMUM
 NICKEL UNDER PLATING : 2~6µm



FPC 挿入側
 FPC INSERTION SIDE
 参考基板レイアウト
**RECOMMENDED PCB
 PATTERN DIMENSIONS (REF.)**

4. FPC について (ABOUT FPC)
 抜き方向は、導体側から補強板側を推奨します
 補強板材質は、ポリイミドを推奨します
 接着剤は熱硬化接着剤を推奨します
 なお、接着剤の接点部への付着は導通不良の原因となりますので染み出しがないよう、お願いします
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
 RECOMMENDED MATERIAL:
 STIFFENER BOARD: POLYIMIDE
 BONDING AGENT: THERMOSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY

FPC 構成材料例
 EXAMPLE OF FPC
 COMPOSITION MATERIAL

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REDRAW	2015/12/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION UNITS	SCALE	 0.25 PITCH FPC CONN E/O HGT=1.65 BTM CONTACT				
	2015/12/24	ANGULAR TOL ± 1.0 °		MM	20:1					
	2015/12/24	4 PLACES ±	VNANDAM	DATE	2015/12/07					
		3 PLACES ±	CHK'D BY	DATE	2015/12/24					
		2 PLACES ±	APP'R BY	DATE	2015/12/24					
		1 PLACE ±	YNOGAWA	DATE	2015/12/24	PRODUCT CUSTOMER DRAWING				
		0 PLACES ±		DRAWING SIZE	THIRD ANGLE PROJECTION	SERIES	MATERIAL NUMBER	CUSTOMER		
				A3		503320	SEE CHART	GENERAL		
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NUMBER		DOC TYPE	DOC PART	SHEET NUMBER
						5033201000		PSD	000	2 OF 2